| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L1 | 3906 | substrate and ground and (via through adj hole) and die and bond$4 and ( pad contact) and wire adj bond$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/01/05 13:27 |
| L2 | 56 | (substrate and ground and (via through adj hole) and die and bond$4 and ( pad contact) and wire adj bond$4 ).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/01/05 13:30 |
| L3 | 34 | (substrate and ground and (via through adj hole) and die and bond$4 and ( pad contact) and ( line stripline microstrip conductor trace) and wire adj bond$4 ).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/01/05 13:35 |
| L4 | 3724 | (substrate and ground and (via through adj hole) and die and bond$4 and ( pad contact) and ( line stripline microstrip conductor trace) and wire adj bond$4 ) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/01/05 13:36 |
| L5 | 93 | (substrate same ground same (via through adj hole) same die same bond$4 same ( pad contact) same ( line stripline microstrip conductor trace) same wire adj bond$4 ) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/01/05 13:36 |
| L6 | 76 | 5 not (2 3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/01/05 13:43 |
| L7 | 4005 | ((333/246) or (333/247) or (333/33) or (333/238) or (333/260)).CCLS. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/01/05 13:43 |
| L8 | 68 | 7 and @pd>="20050713" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/01/05 13:44 |